Title (en)
METHOD FOR PROTECTING AN INTEGRATED CIRCUIT CHIP

Title (de)
VERFAHREN ZUM SCHUTZ EINES INTEGRIERTEN SCHALTUNGSCHIP

Title (fr)
PROCEDE DE PROTECTION DE PUCE DE CIRCUIT INTEGRE

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Application
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Abstract (en)
[origin: FR2788375A1] The invention concerns a method for protecting integrated circuit chips (100) of a silicon wafer (10) comprising the following steps: cutting out the silicon wafer (10) so as to disengage the chips from the integrated circuit; applying a fluid insulating material (150) on the rear surface (104) of the wafer so as to coat the flanks (106) of each chip (100) of the integrated circuit with a thin insulating layer. The insulating material may be applied by spraying, screen printing, dip coating, casting or any other means. The invention further concerns integrated circuit chips whereof the flanks are protected by an insulating material to prevent electrical malfunction caused by contact of a conductive material on the flanks of the chips.

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